Infineon Technologies - XC167CI16F40FBBKXUMA1 Datasheet

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Details	
Product Status	Last Time Buy
Core Processor	C166SV2
Core Size	16-Bit
Speed	40MHz
Connectivity	CANbus, EBI/EMI, I²C, LINbus, SPI, UART/USART
Peripherals	PWM, WDT
Number of I/O	103
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 2.7V
Data Converters	A/D 16x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	PG-TQFP-144-7
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xc167ci16f40fbbkxuma1

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2.2 Pin Configuration and Definition

The pins of the XC167 are described in detail in **Table 2**, including all their alternate functions. **Figure 2** summarizes all pins in a condensed way, showing their location on the 4 sides of the package. E*) and C*) mark pins to be used as alternate external interrupt inputs, C*) marks pins that can have CAN interface lines assigned to them.

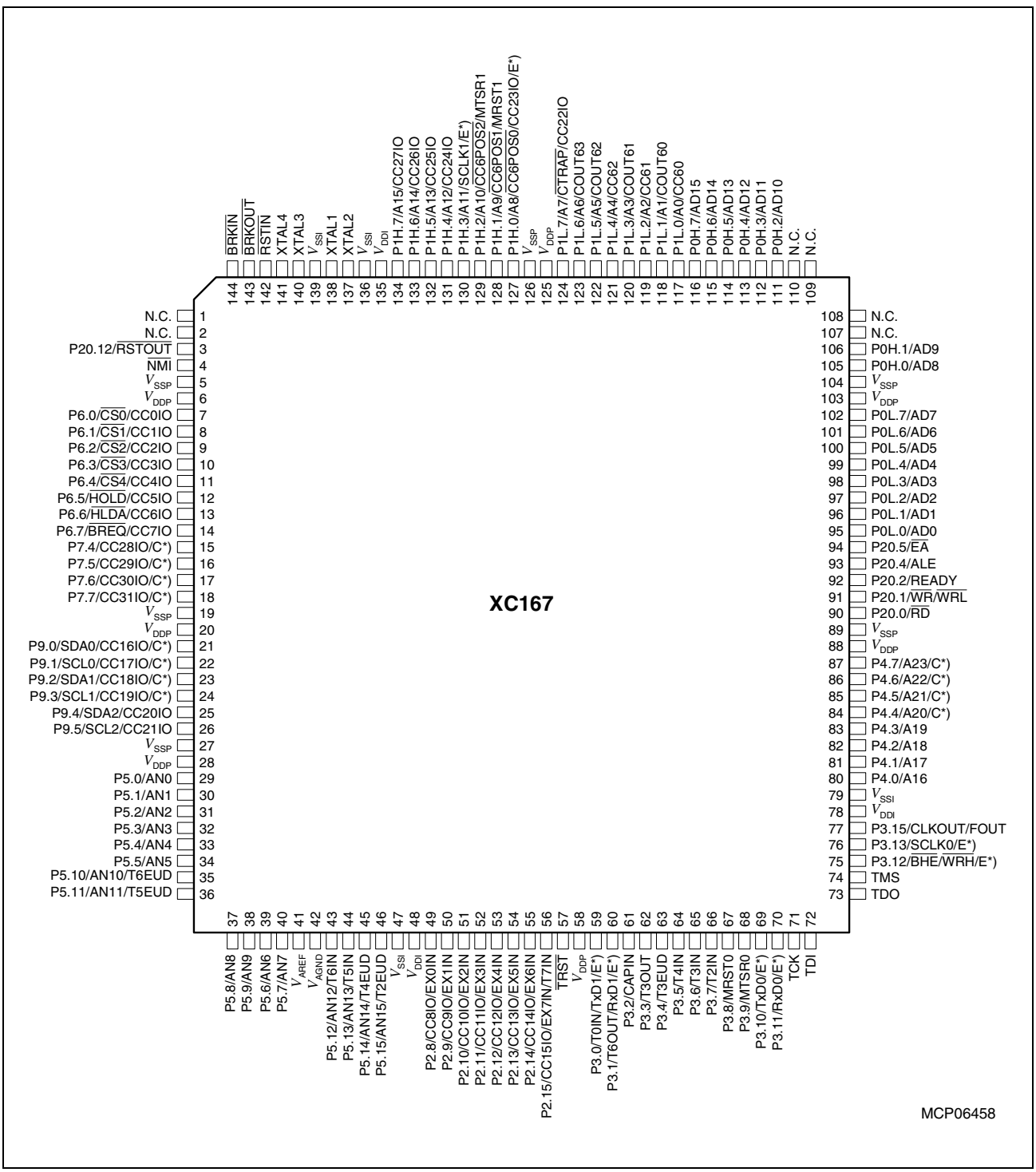


Figure 2 Pin Configuration (top view)

Table 2 Pin Definitions and Functions (cont'd)

Sym-bol	Pin Num.	Input Outp.	Function	
P3		IO	Port 3 is a 15-bit bidirectional I/O port. Each pin can be programmed for input (output driver in high-impedance state) or output (configurable as push/pull or open drain driver). The input threshold of Port 3 is selectable (standard or special). The following Port 3 pins also serve for alternate functions:	
P3.0	59	I	T0IN	CAPCOM1 Timer T0 Count Input,
		O	TxD1	ASC1 Clock/Data Output (Async./Sync),
		I	EX1IN	Fast External Interrupt 1 Input (alternate pin B)
P3.1	60	O	T6OUT	GPT2 Timer T6 Toggle Latch Output,
		I/O	RxD1	ASC1 Data Input (Async.) or Inp./Outp. (Sync.),
		I	EX1IN	Fast External Interrupt 1 Input (alternate pin A)
P3.2	61	I	CAPIN	GPT2 Register CAPREL Capture Input
P3.3	62	O	T3OUT	GPT1 Timer T3 Toggle Latch Output
P3.4	63	I	T3EUD	GPT1 Timer T3 External Up/Down Control Input
P3.5	64	I	T4IN	GPT1 Timer T4 Count/Gate/Reload/Capture Inp
P3.6	65	I	T3IN	GPT1 Timer T3 Count/Gate Input
P3.7	66	I	T2IN	GPT1 Timer T2 Count/Gate/Reload/Capture Inp
P3.8	67	I/O	MRST0	SSC0 Master-Receive/Slave-Transmit In/Out.
P3.9	68	I/O	MTSR0	SSC0 Master-Transmit/Slave-Receive Out/In.
P3.10	69	O	TxD0	ASC0 Clock/Data Output (Async./Sync.),
		I	EX2IN	Fast External Interrupt 2 Input (alternate pin B)
P3.11	70	I/O	RxD0	ASC0 Data Input (Async.) or Inp./Outp. (Sync.),
		I	EX2IN	Fast External Interrupt 2 Input (alternate pin A)
P3.12	75	O	$\overline{\text{BHE}}$	External Memory High Byte Enable Signal,
		O	$\overline{\text{WRH}}$	External Memory High Byte Write Strobe,
		I	EX3IN	Fast External Interrupt 3 Input (alternate pin B)
P3.13	76	I/O	SCLK0	SSC0 Master Clock Output/Slave Clock Input.,
		I	EX3IN	Fast External Interrupt 3 Input (alternate pin A)
P3.15	77	O	CLKOUT	Master Clock Output,
		O	FOUT	Programmable Frequency Output
TCK	71	I	Debug System: JTAG Clock Input	
TDI	72	I	Debug System: JTAG Data In	
TDO	73	O	Debug System: JTAG Data Out	
TMS	74	I	Debug System: JTAG Test Mode Selection	

Table 2 Pin Definitions and Functions (cont'd)

Sym-bol	Pin Num.	Input Outp.	Function
XTAL2 XTAL1	137 138	O I	XTAL2: Output of the main oscillator amplifier circuit XTAL1: Input to the main oscillator amplifier and input to the internal clock generator To clock the device from an external source, drive XTAL1, while leaving XTAL2 unconnected. Minimum and maximum high/low and rise/fall times specified in the AC Characteristics must be observed. *Note: Input pin XTAL1 belongs to the core voltage domain. Therefore, input voltages must be within the range defined for V_{DDI}.*
XTAL3 XTAL4	140 141	I O	XTAL3: Input to the auxiliary (32-kHz) oscillator amplifier XTAL4: Output of the auxiliary (32-kHz) oscillator amplifier circuit To clock the device from an external source, drive XTAL3, while leaving XTAL4 unconnected. Minimum and maximum high/low and rise/fall times specified in the AC Characteristics must be observed. *Note: Input pin XTAL3 belongs to the core voltage domain. Therefore, input voltages must be within the range defined for V_{DDI}.*
$\overline{\text{RSTIN}}$	142	I	Reset Input with Schmitt-Trigger characteristics. A low-level at this pin while the oscillator is running resets the XC167. A spike filter suppresses input pulses < 10 ns. Input pulses > 100 ns safely pass the filter. The minimum duration for a safe recognition should be 100 ns + 2 CPU clock cycles. *Note: The reset duration must be sufficient to let the hardware configuration signals settle.* *External circuitry must guarantee low-level at the $\overline{\text{RSTIN}}$ pin at least until both power supply voltages have reached the operating range.*
$\overline{\text{BRK OUT}}$	143	O	Debug System: Break Out
$\overline{\text{BRKIN}}$	144	I	Debug System: Break In
NC	1, 2, 107 - 110	–	No connection. It is recommended not to connect these pins to the PCB.

The EBC also controls accesses to resources connected to the on-chip LXBus. The LXBus is an internal representation of the external bus and allows accessing integrated peripherals and modules in the same way as external components.

The TwinCAN module is connected and accessed via the LXBus.

Table 4 XC167 Interrupt Nodes (cont'd)

Source of Interrupt or PEC Service Request	Control Register	Vector Location[1)]	Trap Number
ASC1 Autobaud	ASC1_ABIC	xx'0108$_H$	42$_H$ / 66$_D$
End of PEC Subchannel	EOPIC	xx'0130$_H$	4C$_H$ / 76$_D$
CAPCOM6 Timer T12	CCU6_T12IC	xx'0134$_H$	4D$_H$ / 77$_D$
CAPCOM6 Timer T13	CCU6_T13IC	xx'0138$_H$	4E$_H$ / 78$_D$
CAPCOM6 Emergency	CCU6_EIC	xx'013C$_H$	4F$_H$ / 79$_D$
CAPCOM6	CCU6_IC	xx'0140$_H$	50$_H$ / 80$_D$
SSC1 Transmit	SSC1_TIC	xx'0144$_H$	51$_H$ / 81$_D$
SSC1 Receive	SSC1_RIC	xx'0148$_H$	52$_H$ / 82$_D$
SSC1 Error	SSC1_EIC	xx'014C$_H$	53$_H$ / 83$_D$
CAN0	CAN_0IC	xx'0150$_H$	54$_H$ / 84$_D$
CAN1	CAN_1IC	xx'0154$_H$	55$_H$ / 85$_D$
CAN2	CAN_2IC	xx'0158$_H$	56$_H$ / 86$_D$
CAN3	CAN_3IC	xx'015C$_H$	57$_H$ / 87$_D$
CAN4	CAN_4IC	xx'0164$_H$	59$_H$ / 89$_D$
CAN5	CAN_5IC	xx'0168$_H$	5A$_H$ / 90$_D$
CAN6	CAN_6IC	xx'016C$_H$	5B$_H$ / 91$_D$
CAN7	CAN_7IC	xx'0170$_H$	5C$_H$ / 92$_D$
RTC	RTC_IC	xx'0174$_H$	5D$_H$ / 93$_D$
Unassigned node	–	xx'012C$_H$	4B$_H$ / 75$_D$
Unassigned node	–	xx'00FC$_H$	3F$_H$ / 63$_D$
Unassigned node	–	xx'0160$_H$	58$_H$ / 88$_D$

1) Register VECSEG defines the segment where the vector table is located to.
Bitfield VECSC in register CPUCON1 defines the distance between two adjacent vectors. This table represents the default setting, with a distance of 4 (two words) between two vectors.

3.9 Real Time Clock

The Real Time Clock (RTC) module of the XC167 is directly clocked via a separate clock driver either with the on-chip auxiliary oscillator frequency (f_{RTC} = f_{OSCa}) or with the prescaled on-chip main oscillator frequency (f_{RTC} = f_{OSCm}/32). It is therefore independent from the selected clock generation mode of the XC167.

The RTC basically consists of a chain of divider blocks:

- a selectable 8:1 divider (on - off)
- the reloadable 16-bit timer T14
- the 32-bit RTC timer block (accessible via registers RTCH and RTCL), made of:
  - a reloadable 10-bit timer
  - a reloadable 6-bit timer
  - a reloadable 6-bit timer
  - a reloadable 10-bit timer

All timers count up. Each timer can generate an interrupt request. All requests are combined to a common node request.

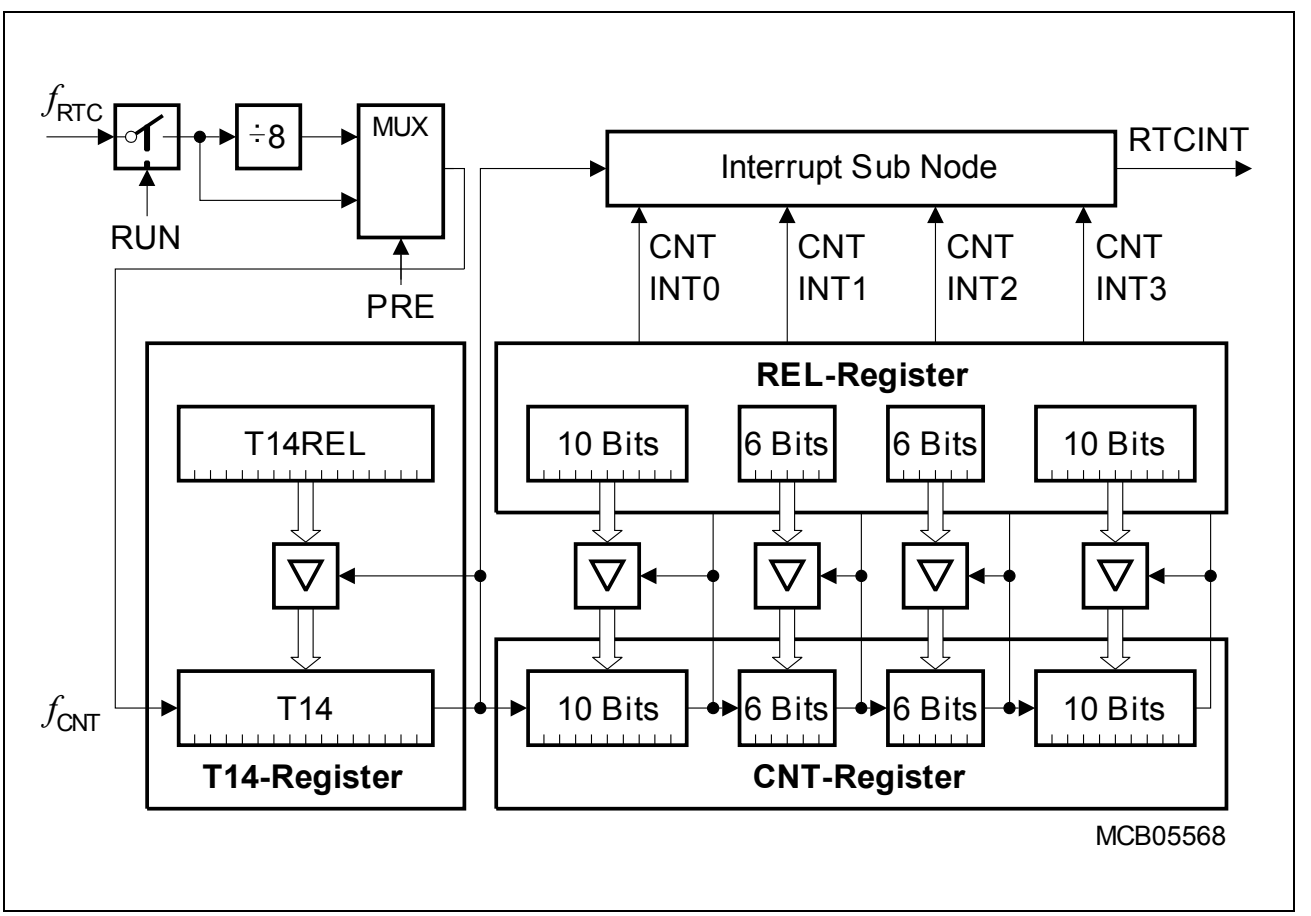


Figure 9 RTC Block Diagram

Note: The registers associated with the RTC are not affected by a reset in order to maintain the correct system time even when intermediate resets are executed.

Table 7 Summary of the XC167's Parallel Ports

Port	Control	Alternate Functions
PORT0	Pad drivers	Address/Data lines or data lines[1]
PORT1	Pad drivers	Address lines[2]
		Capture inputs or compare outputs, Serial interface lines
Port 2	Pad drivers, Open drain, Input threshold	Capture inputs or compare outputs, Timer control signal, Fast external interrupt inputs
Port 3	Pad drivers, Open drain, Input threshold	Timer control signals, serial interface lines, Optional bus control signal $\overline{BHE}$/$\overline{WRH}$, System clock output CLKOUT (or FOUT)
Port 4	Pad drivers, Open drain, Input threshold	Segment address lines[3]
		CAN interface lines[4]
Port 5	–	Analog input channels to the A/D converter, Timer control signals
Port 6	Open drain, Input threshold	Capture inputs or compare outputs, Bus arbitration signals $\overline{BREQ}$, $\overline{HLDA}$, $\overline{HOLD}$, Optional chip select signals
Port 7	Open drain, Input threshold	Capture inputs or compare outputs, CAN interface lines[4]
Port 9	Pad drivers, Open drain, Input threshold	Capture inputs or compare outputs
		CAN interface lines[4], IIC bus interface lines[4]
Port 20	Pad drivers, Open drain	Bus control signals $\overline{RD}$, $\overline{WR}$/$\overline{WRL}$, READY, ALE, External access enable pin $\overline{EA}$, Reset indication output $\overline{RSTOUT}$

1) For multiplexed bus cycles.

2) For demultiplexed bus cycles.

3) For more than 64 Kbytes of external resources.

4) Can be assigned by software.

3.18 Power Management

The XC167 provides several means to control the power it consumes either at a given time or averaged over a certain timespan. Three mechanisms can be used (partly in parallel):

- **Power Saving Modes** switch the XC167 into a special operating mode (control via instructions).
  Idle Mode stops the CPU while the peripherals can continue to operate.
  Sleep Mode and Power Down Mode stop all clock signals and all operation (RTC may optionally continue running). Sleep Mode can be terminated by external interrupt signals.
- **Clock Generation Management** controls the distribution and the frequency of internal and external clock signals. While the clock signals for currently inactive parts of logic are disabled automatically, the user can reduce the XC167's CPU clock frequency which drastically reduces the consumed power.
  External circuitry can be controlled via the programmable frequency output FOUT.
- **Peripheral Management** permits temporary disabling of peripheral modules (control via register SYSCON3). Each peripheral can separately be disabled/enabled.

The on-chip RTC supports intermittent operation of the XC167 by generating cyclic wake-up signals. This offers full performance to quickly react on action requests while the intermittent sleep phases greatly reduce the average power consumption of the system.

3.19 Instruction Set Summary

Table 8 lists the instructions of the XC167 in a condensed way.
The various addressing modes that can be used with a specific instruction, the operation of the instructions, parameters for conditional execution of instructions, and the opcodes for each instruction can be found in the **"Instruction Set Manual"**.

This document also provides a detailed description of each instruction.

Table 8 Instruction Set Summary

Mnemonic	Description	Bytes
ADD(B)	Add word (byte) operands	2 / 4
ADDC(B)	Add word (byte) operands with Carry	2 / 4
SUB(B)	Subtract word (byte) operands	2 / 4
SUBC(B)	Subtract word (byte) operands with Carry	2 / 4
MUL(U)	(Un)Signed multiply direct GPR by direct GPR (16- × 16-bit)	2
DIV(U)	(Un)Signed divide register MDL by direct GPR (16-/16-bit)	2
DIVL(U)	(Un)Signed long divide reg. MD by direct GPR (32-/16-bit)	2
CPL(B)	Complement direct word (byte) GPR	2
NEG(B)	Negate direct word (byte) GPR	2
AND(B)	Bitwise AND, (word/byte operands)	2 / 4
OR(B)	Bitwise OR, (word/byte operands)	2 / 4
XOR(B)	Bitwise exclusive OR, (word/byte operands)	2 / 4
BCLR/BSET	Clear/Set direct bit	2
BMOV(N)	Move (negated) direct bit to direct bit	4
BAND/BOR/BXOR	AND/OR/XOR direct bit with direct bit	4
BCMP	Compare direct bit to direct bit	4
BFLDH/BFLDL	Bitwise modify masked high/low byte of bit-addressable direct word memory with immediate data	4
CMP(B)	Compare word (byte) operands	2 / 4
CMPD1/2	Compare word data to GPR and decrement GPR by 1/2	2 / 4
CMPI1/2	Compare word data to GPR and increment GPR by 1/2	2 / 4
PRIOR	Determine number of shift cycles to normalize direct word GPR and store result in direct word GPR	2
SHL/SHR	Shift left/right direct word GPR	2

4 Electrical Parameters

4.1 General Parameters

Table 9 Absolute Maximum Ratings

Parameter	Symbol	Limit Values		Unit	Notes
		Min.	Max.		
Storage temperature	T_{ST}	-65	150	°C	1)
Junction temperature	T_J	-40	150	°C	under bias
Voltage on V_{DDI} pins with respect to ground (V_{SS})	V_{DDI}	-0.5	3.25	V	–
Voltage on V_{DDP} pins with respect to ground (V_{SS})	V_{DDP}	-0.5	6.2	V	–
Voltage on any pin with respect to ground (V_{SS})	V_{IN}	-0.5	V_{DDP} + 0.5	V	2)
Input current on any pin during overload condition	–	-10	10	mA	–
Absolute sum of all input currents during overload condition	–	–	|100|	mA	–

1) Moisture Sensitivity Level (MSL) 3, conforming to Jedec J-STD-020C for 260 °C for PG-TQFP-144-7, and 240 °C for P-TQFP-144-19.

2) Input pins XTAL1/XTAL3 belong to the core voltage domain. Therefore, input voltages must be within the range defined for V_{DDI}.

Note: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.
During absolute maximum rating overload conditions ($V_{IN} > V_{DDP}$ or $V_{IN} < V_{SS}$) the voltage on V_{DDP} pins with respect to ground (V_{SS}) must not exceed the values defined by the absolute maximum ratings.

Table 12 Current Limits for Port Output Drivers

Port Output Driver Mode	Maximum Output Current (I_{OLmax}, $-I_{OHmax}$)[1]	Nominal Output Current (I_{OLnom}, $-I_{OHnom}$)
Strong driver	10 mA	2.5 mA
Medium driver	4.0 mA	1.0 mA
Weak driver	0.5 mA	0.1 mA

1) An output current above $|I_{OXnom}|$ may be drawn from up to three pins at the same time. For any group of 16 neighboring port output pins the total output current in each direction (ΣI_{OL} and $\Sigma -I_{OH}$) must remain below 50 mA.

Table 13 Power Consumption XC167 (Operating Conditions apply)

Parameter	Sym-bol	Limit Values		Unit	Test Condition
		Min.	Max.		
Power supply current (active) with all peripherals active	I_{DDI}	–	15 + 2.6 × f_{CPU}	mA	f_{CPU} in [MHz][1)2)]
Pad supply current	I_{DDP}	–	5	mA	[3)]
Idle mode supply current with all peripherals active	I_{IDX}	–	15 + 1.2 × f_{CPU}	mA	f_{CPU} in [MHz][2)]
Sleep and Power down mode supply current caused by leakage[4)]	I_{PDL}[5)]	–	128,000 × $e^{-\alpha}$	mA	V_{DDI} = V_{DDImax}[6)] T_J in [°C] α = 4670 / (273 + T_J)
Sleep and Power down mode supply current caused by leakage and the RTC running, clocked by the main oscillator[4)]	I_{PDM}[7)]	–	0.6 + 0.02 × f_{OSC} + I_{PDL}	mA	V_{DDI} = V_{DDImax} f_{OSC} in [MHz]
Sleep and Power down mode supply current caused by leakage and the RTC running, clocked by the auxiliary oscillator at 32 kHz[4)]	I_{PDA}	–	0.1 + I_{PDL}	mA	V_{DDI} = V_{DDImax}

1) During Flash programming or erase operations the supply current is increased by max. 5 mA.

2) The supply current is a function of the operating frequency. This dependency is illustrated in **Figure 11**. These parameters are tested at V_{DDImax} and maximum CPU clock frequency with all outputs disconnected and all inputs at V_{IL} or V_{IH}.

3) The pad supply voltage pins (V_{DDP}) mainly provides the current consumed by the pin output drivers. A small amount of current is consumed even though no outputs are driven, because the drivers' input stages are switched and also the Flash module draws some power from the V_{DDP} supply.

4) The total supply current in Sleep and Power down mode is the sum of the temperature dependent leakage current and the frequency dependent current for RTC and main oscillator or auxiliary oscillator (if active).
5) This parameter is determined mainly by the transistor leakage currents. This current heavily depends on the junction temperature (see **Figure 13**). The junction temperature T_J is the same as the ambient temperature T_A if no current flows through the port output drivers. Otherwise, the resulting temperature difference must be taken into account.
6) All inputs (including pins configured as inputs) at 0 V to 0.1 V or at V_{DDP} - 0.1 V to V_{DDP}, all outputs (including pins configured as outputs) disconnected. This parameter is tested at 25 °C and is valid for $T_J \geq 25$ °C.
7) This parameter is determined mainly by the current consumed by the oscillator switched to low gain mode (see **Figure 12**). This current, however, is influenced by the external oscillator circuitry (crystal, capacitors). The given values refer to a typical circuitry and may change in case of a not optimized external oscillator circuitry.

4.4.3 External Clock Drive XTAL1

Table 19 External Clock Drive Characteristics (Operating Conditions apply)

Parameter	Symbol		Limit Values		Unit
			Min.	Max.	
Oscillator period	t_{OSC}	SR	25	250[1)]	ns
High time[2)]	t_1	SR	6	–	ns
Low time[2)]	t_2	SR	6	–	ns
Rise time[2)]	t_3	SR	–	8	ns
Fall time[2)]	t_4	SR	–	8	ns

1) The maximum limit is only relevant for PLL operation to ensure the minimum input frequency for the PLL.

2) The clock input signal must reach the defined levels V_{ILC} and V_{IHC}.

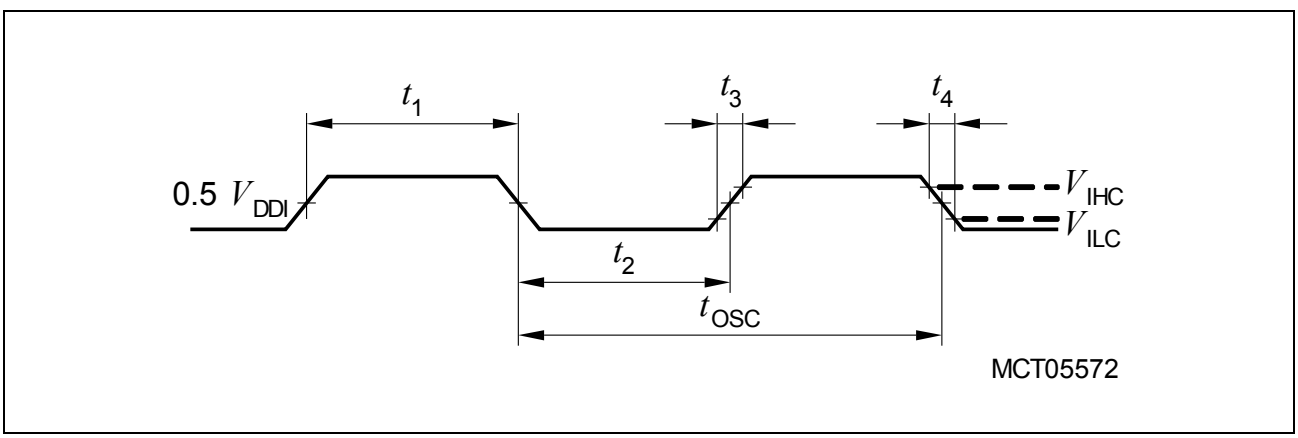
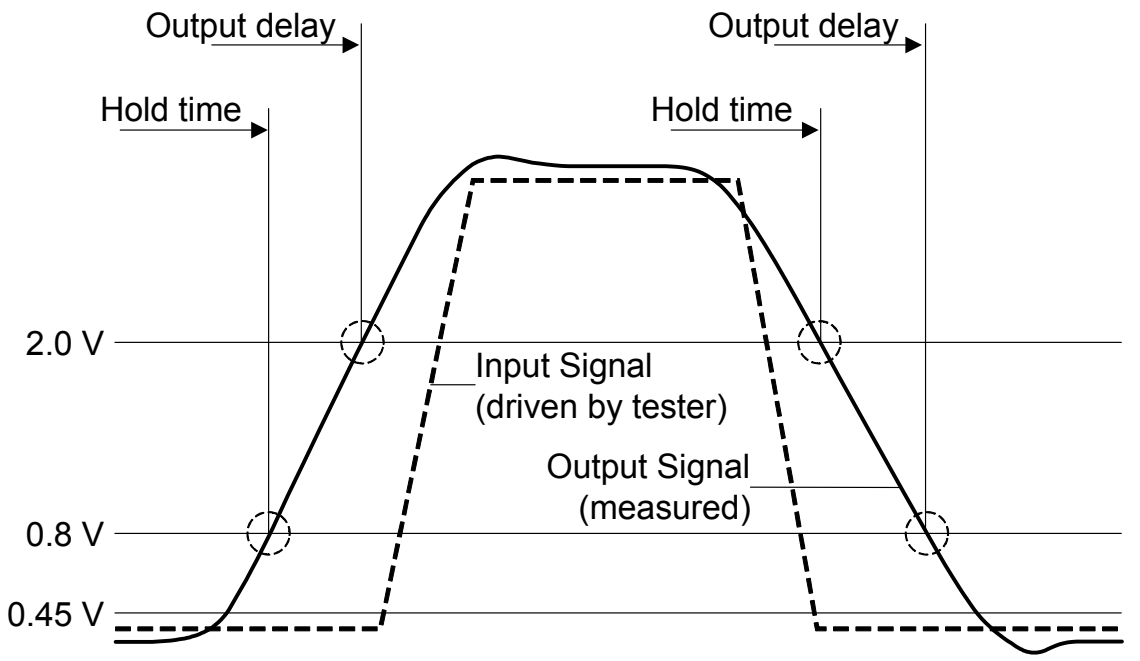


Figure 17 External Clock Drive XTAL1

Note: If the on-chip oscillator is used together with a crystal or a ceramic resonator, the oscillator frequency is limited to a range of 4 MHz to 16 MHz.
It is strongly recommended to measure the oscillation allowance (negative resistance) in the final target system (layout) to determine the optimum parameters for the oscillator operation. Please refer to the limits specified by the crystal supplier.
When driven by an external clock signal it will accept the specified frequency range. Operation at lower input frequencies is possible but is verified by design only (not subject to production test).

4.4.4 Testing Waveforms



Output timings refer to the rising edge of CLKOUT.
Input timings are calculated from the time, when the input signal reaches V_{IH} or V_{IL}, respectively.

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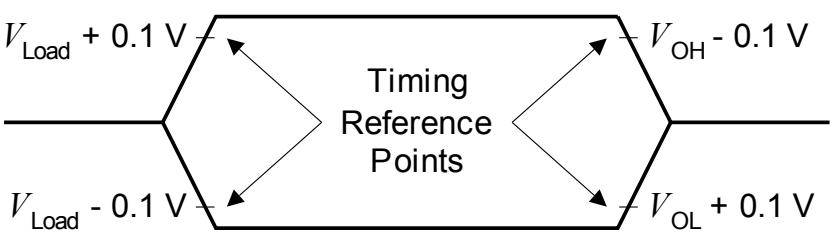
Figure 18 Input Output Waveforms



For timing purposes a port pin is no longer floating when a 100 mV change from load voltage occurs, but begins to float when a 100 mV change from the loaded V_{OH}/V_{OL} level occurs (I_{OH}/I_{OL} = 20 mA).

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Figure 19 Float Waveforms

Variable Memory Cycles

External bus cycles of the XC167 are executed in five subsequent cycle phases (AB, C, D, E, F). The duration of each cycle phase is programmable (via the TCONCSx registers) to adapt the external bus cycles to the respective external module (memory, peripheral, etc.).

The duration of the access phase can optionally be controlled by the external module via the READY handshake input.

This table provides a summary of the phases and the respective choices for their duration.

Table 21 Programmable Bus Cycle Phases (see timing diagrams)

Bus Cycle Phase	Parameter	Valid Values	Unit
Address setup phase, the standard duration of this phase (1 … 2 TCP) can be extended by 0 … 3 TCP if the address window is changed	tp_{AB}	1 … 2 (5)	TCP
Command delay phase	tp_{C}	0 … 3	TCP
Write Data setup/MUX Tristate phase	tp_{D}	0 … 1	TCP
Access phase	tp_{E}	1 … 32	TCP
Address/Write Data hold phase	tp_{F}	0 … 3	TCP

Note: The bandwidth of a parameter (minimum and maximum value) covers the whole operating range (temperature, voltage) as well as process variations. Within a given device, however, this bandwidth is smaller than the specified range. This is also due to interdependencies between certain parameters. Some of these interdependencies are described in additional notes (see standard timing).

Bus Cycle Control via READY Input

The duration of an external bus cycle can be controlled by the external circuitry via the READY input signal. The polarity of this input signal can be selected.

Synchronous READY permits the shortest possible bus cycle but requires the input signal to be synchronous to the reference signal CLKOUT.

Asynchronous READY puts no timing constraints on the input signal but incurs one waitstate minimum due to the additional synchronization stage. The minimum duration of an asynchronous READY signal to be safely synchronized must be one CLKOUT period plus the input setup time.

An active READY signal can be deactivated in response to the trailing (rising) edge of the corresponding command ($\overline{RD}$ or $\overline{WR}$).

If the next following bus cycle is READY-controlled, an active READY signal must be disabled before the first valid sample point for the next bus cycle. This sample point depends on the programmed phases of the next following cycle.

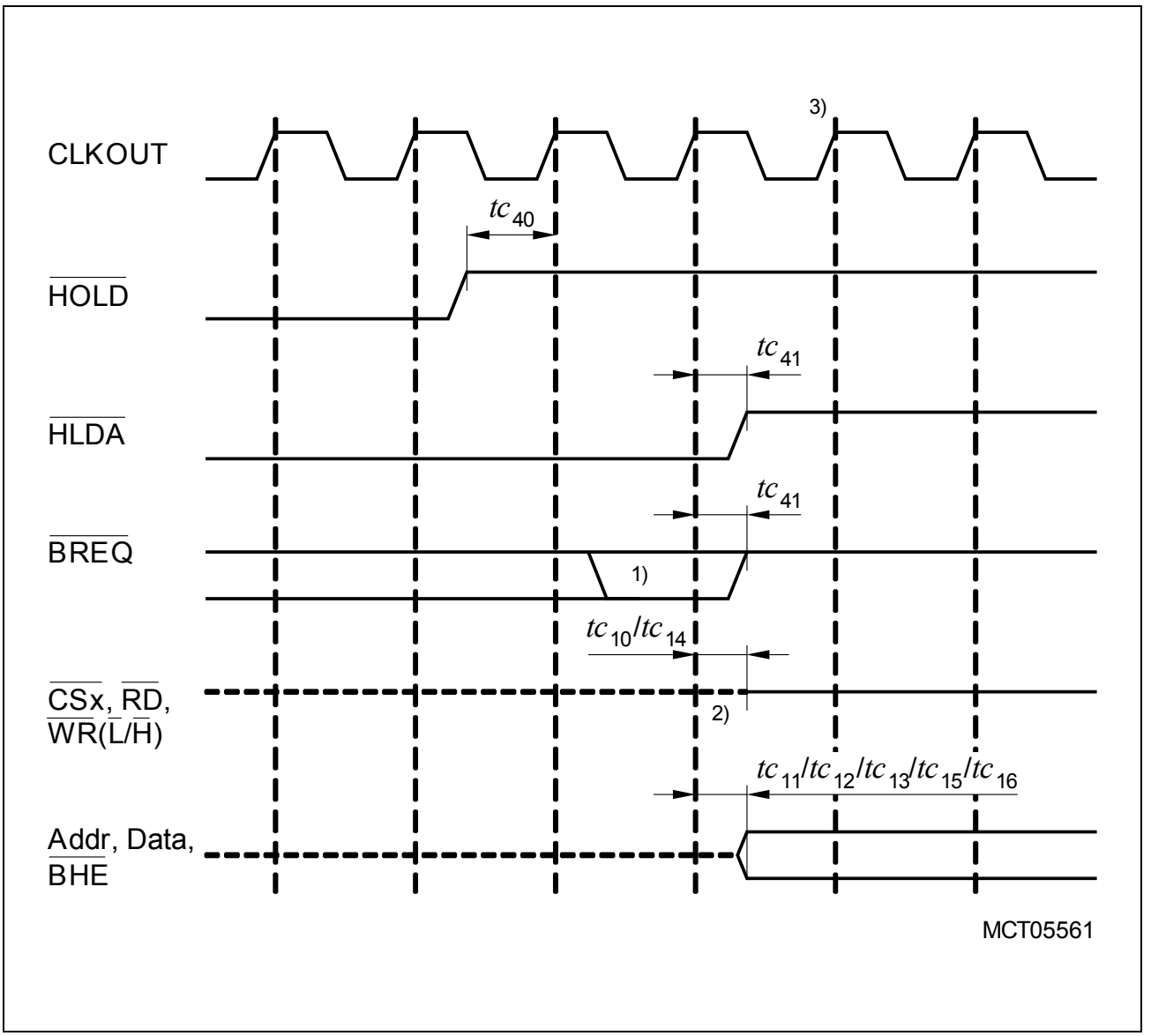
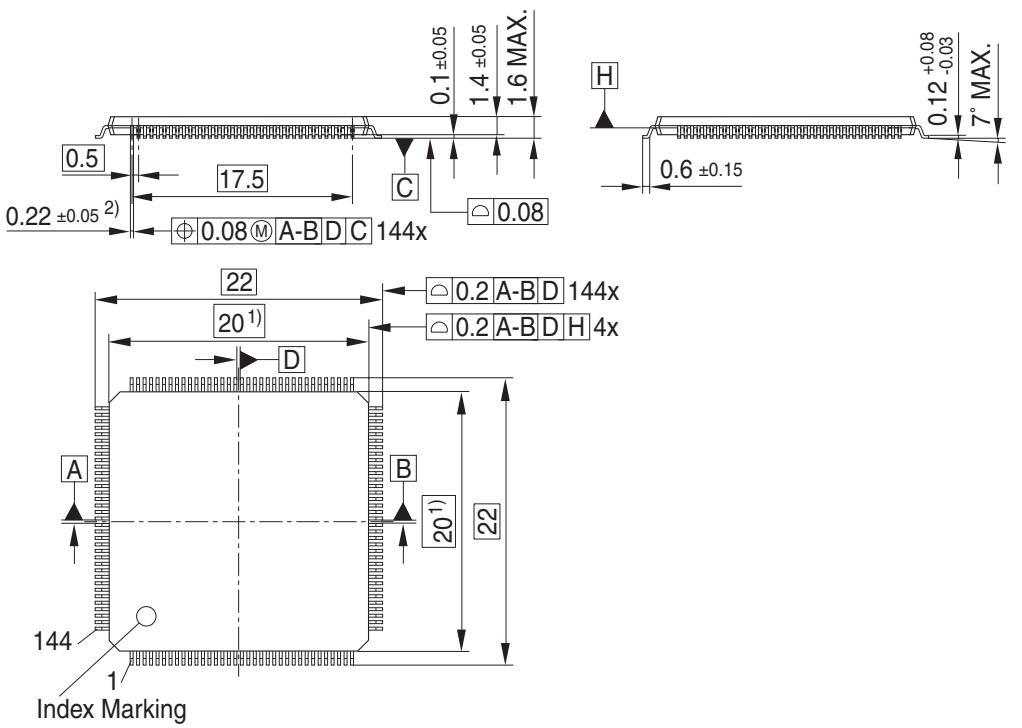


Figure 25 External Bus Arbitration, Regaining the Bus

Notes

1. *This is the last chance for $\overline{BREQ}$ to trigger the indicated regain-sequence. Even if $\overline{BREQ}$ is activated earlier, the regain-sequence is initiated by $\overline{HOLD}$ going high. Please note that $\overline{HOLD}$ may also be deactivated without the XC167 requesting the bus.*
2. *The control outputs will be resistive high (pull-up) before being driven inactive (ALE will be low).*
3. *The next XC167 driven bus cycle may start here.*



1) Does not include plastic or metal protrusion of 0.25 max. per side
2) Does not include dambar protrusion of 0.08 max. per side

GPP09243

Figure 27 **P-TQFP-144-19** (Plastic Thin Quad Flat Package)

You can find all of our packages, sorts of packing and others in our Infineon Internet Page “Products”: **http://www.infineon.com/products**. Dimensions in mm

5.2 Flash Memory Parameters

The data retention time of the XC167's Flash memory (i.e. the time after which stored data can still be retrieved) depends on the number of times the Flash memory has been erased and programmed.

Table 25 Flash Parameters (XC167, 128 Kbytes)

Parameter	Symbol	Limit Values		Unit	Notes
		Min.	Max.		
Data retention time	t_{RET}	15	–	years	10^3 erase/program cycles
Flash Erase Endurance	N_{ER}	20×10^3	–	cycles	Data retention time 5 years